

TOSHIBA INFRARED LED GaAs INFRARED EMITTER

TLN104, TLN104(LB)

INFRARED LEDS FOR PHOTODIODES

Unit : mm

TAPE AND CARD READERS
 HANDHELD TERMINALS
 AUDIO AND VIDEO EQUIPMENT
 OPTO-ELECTRONIC SWITCHES

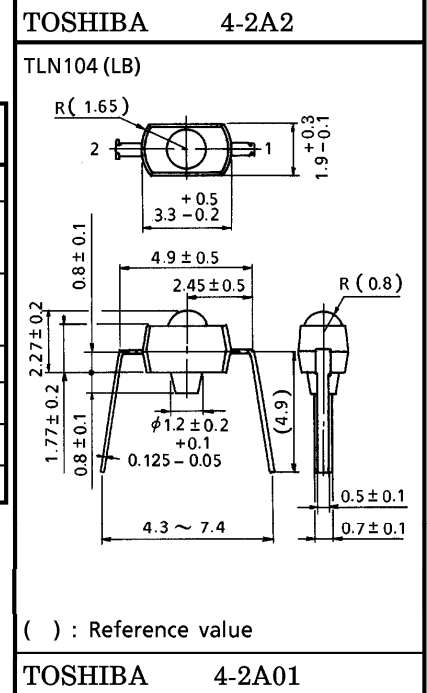
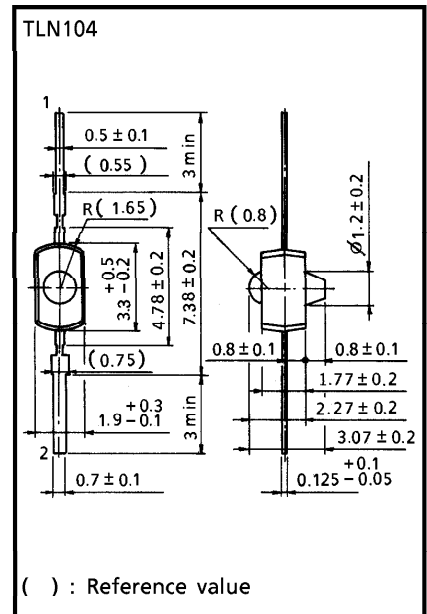
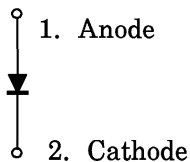
- Micro-package (epoxy-resin package)
 Double-ended type : TLN104
 DIP type : TLN104 (LB)
- Can be mounted with 2.5 mm pitch.
- High radiant power : $P_o = 3 \text{ mW}$ (typ.)
- Excellent radiant-intensity linearity. Modulation by pulse operation and high frequency is possible.
- Half-angle value : $\theta_{\frac{1}{2}} = \pm 20^\circ$ (typ.)

MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current	I_F	40	mA
Forward Current Derating ($T_a > 25^\circ\text{C}$)	$\Delta I_F / ^\circ\text{C}$	-0.53	mA / $^\circ\text{C}$
Pulse Forward Current	I_{FP} (Note 1)	400	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-25~85	$^\circ\text{C}$
Storage Temperature	T_{stg}	-30~100	$^\circ\text{C}$
Soldering Temperature (3 s)	T_{sol}	260	$^\circ\text{C}$

(Note 1) : Pulse width $\leq 100 \mu\text{s}$, repetitive frequency = 100 Hz

PIN CONNECTION



TOSHIBA 4-2A01
 Weight : 0.02 g (typ.)

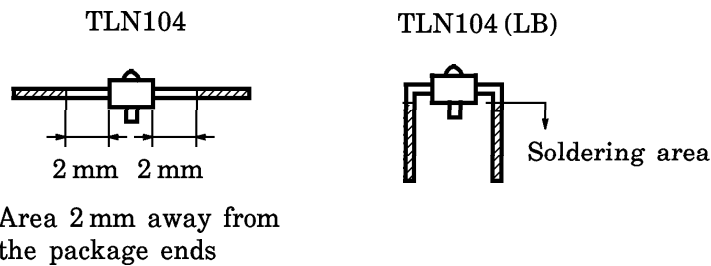
OPTICAL AND ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	Min	Typ.	Max	UNIT	
Forward Voltage	V _F	I _F = 10 mA	—	1.13	1.35	V	
Reverse Current	I _R	V _R = 5 V	—	—	10	μA	
Radiant Power	P _O	I _F = 20 mA	TLN104	1.5	3	—	mW
			TLN104 (B)	2.5	—	6.0	
			TLN104 (LB)	1.5	3	—	
			TLN104 (B, LB)	2.5	—	6.0	
Capacitance	C _T	V _R = 0, f = 1 MHz	—	50	—	pF	
Peak Emission Wavelength	λ _P	I _F = 20 mA	—	940	—	nm	
Spectral Line Half Width	Δλ	I _F = 20 mA	—	50	—	nm	
Half Value Angle	θ _½	I _F = 20 mA	—	±20	—	°	

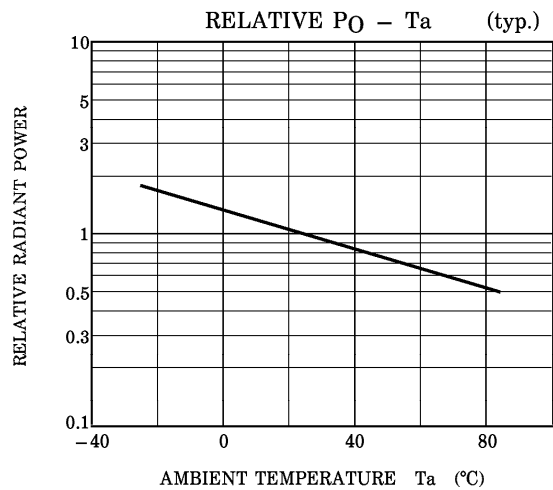
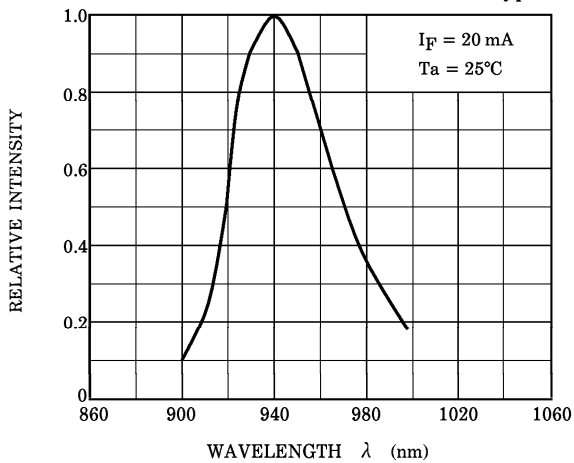
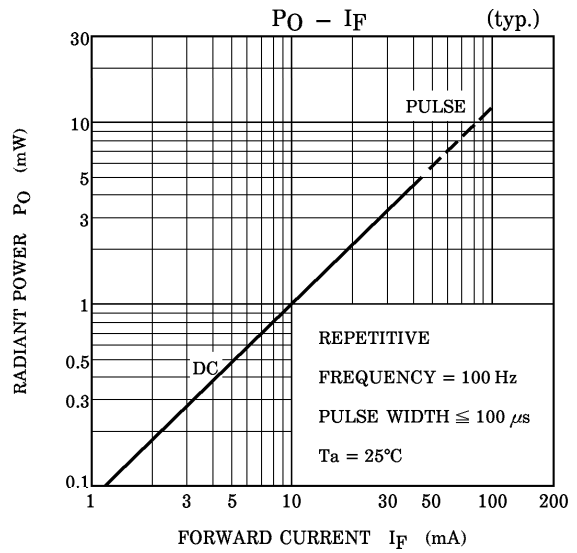
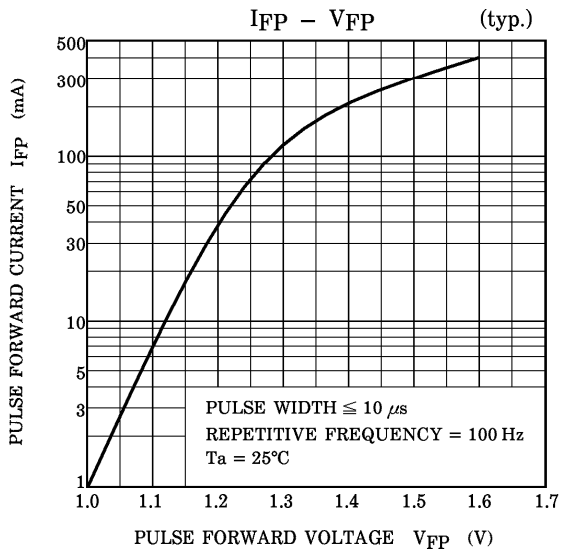
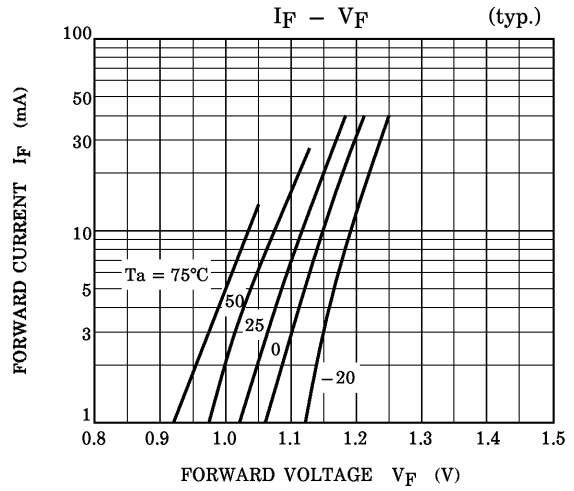
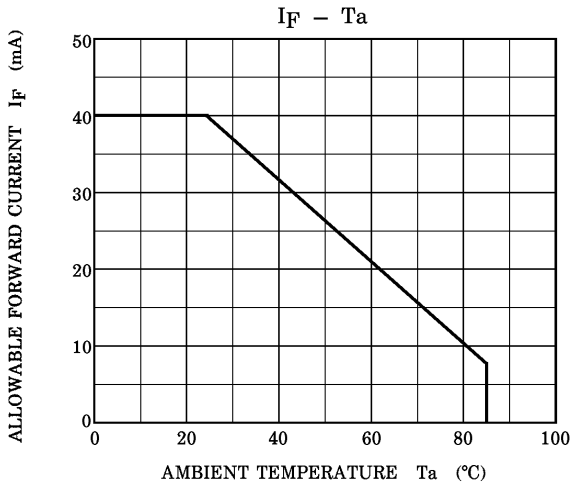
PRECAUTIONS

Please be careful of the followings.

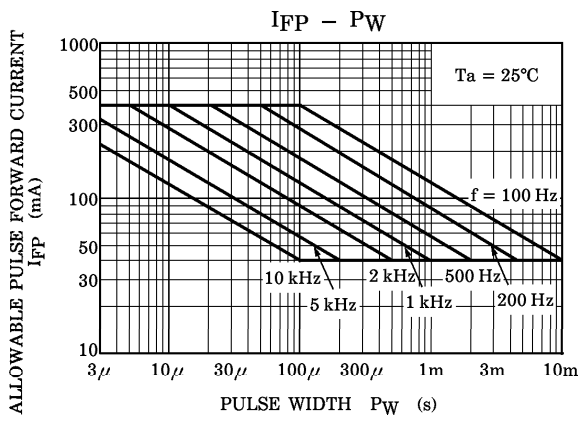
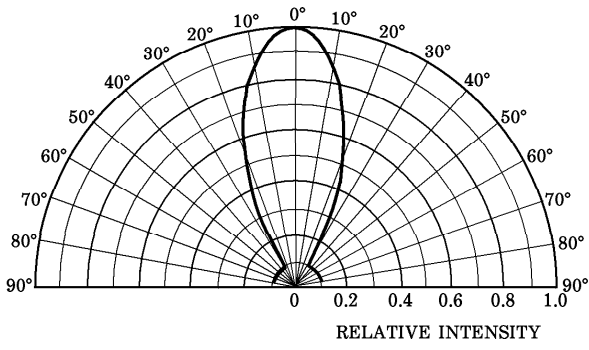
- When forming the leads, bend each lead under the 0.8 mm from the body of the device.
Soldering must be performed after the leads have been formed. However, in case of TLN104 (LB), no lead forming shall be performed.
- Soldering shall be performed within the range shown below.



- Radiant power falls over time due to the current which flows in the infrared LED.
When designing a circuit, take into account this change in radiant power over time.



RADIATION PATTERN (typ.)
($T_a = 25^\circ\text{C}$)



RESTRICTIONS ON PRODUCT USE

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